

Title (en)  
FORMULATION FOR AN INSULATION SYSTEM AND INSULATION SYSTEM

Title (de)  
FORMULIERUNG FÜR EIN ISOLIERSYSTEM UND ISOLIERSYSTEM

Title (fr)  
FORMULATION POUR UN SYSTÈME ISOLANT ET SYSTÈME ISOLANT

Publication  
**EP 3174907 A1 20170607 (DE)**

Application  
**EP 15774537 A 20150922**

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Abstract (en)  
[origin: WO2016050557A1] The invention relates to a novel formulation for an insulation system that has a higher erosion resistance and that can be used in the form of a casting or compression-molding resin as insulation for conductors and/or insulation for the walls of current-carrying conductors in generators, motors and/or rotary machines. The formulation comprises isotropic and spheric nanofiller particles in a weight percentage of up to 25% having organic and inorganic portions.

IPC 8 full level  
**C08C 19/25** (2006.01); **H01B 3/00** (2006.01); **H01B 3/40** (2006.01); **H01B 3/46** (2006.01)

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Citation (search report)  
See references of WO 2016050557A1

Citation (examination)  
ALAN. J. WADDON ET AL: "Crystal Structure of Polyhedral Oligomeric Silsequioxane (POSS) Nano-materials: A Study by X-ray Diffraction and Electron Microscopy", CHEMISTRY OF MATERIALS, vol. 15, no. 24, 1 December 2003 (2003-12-01), pages 4555 - 4561, XP055468238, ISSN: 0897-4756, DOI: 10.1021/cm034308b

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**DE 102014219765 A 20140930**; CN 201580052838 A 20150922; EP 15774537 A 20150922; EP 2015071691 W 20150922; JP 2017517303 A 20150922; US 201515515770 A 20150922